



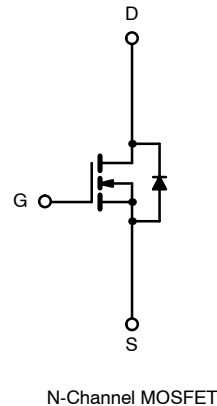
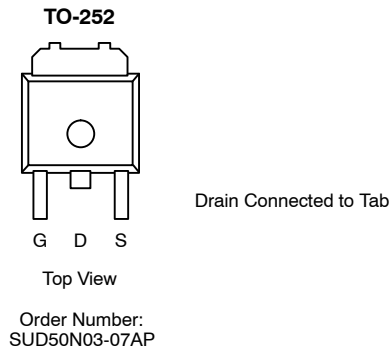
N-Channel 30-V (D-S) 175°C MOSFET

PRODUCT SUMMARY

V_{DS} (V)	$r_{DS(on)}$ (Ω)	I_D (A) ^{a, b}
30	0.007 @ $V_{GS} = 10$ V	81 ^c
	0.010 @ $V_{GS} = 4.5$ V	67 ^c

FEATURES

- TrenchFET® Power MOSFET
- 175°C Maximum Junction Temperature
- 100% R_g Tested

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ UNLESS OTHERWISE NOTED)

Parameter		Symbol	Limit	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	
Continuous Drain Current ($T_J = 175^\circ\text{C}$) ^{a, b}	$T_C = 25^\circ\text{C}$	I_D	81 ^c	A
	$T_C = 100^\circ\text{C}$		57 ^c	
Pulsed Drain Current		I_{DM}	100	
Continuous Source Current (Diode Conduction) ^{a, b}		I_S	25	
Maximum Power Dissipation	$T_C = 25^\circ\text{C}$	P_D	88	W
	$T_A = 25^\circ\text{C}$		8.3 ^{a, b}	
Operating Junction and Storage Temperature Range		T_J, T_{stg}	-55 to 175	$^\circ\text{C}$

THERMAL RESISTANCE RATINGS

Parameter		Symbol	Typical	Maximum	Unit
Junction-to-Ambient ^a	$t \leq 10$ sec	R_{thJA}	15	18	$^\circ\text{C/W}$
	Steady State		40	50	
Junction-to-Case		R_{thJC}	1.4	1.7	

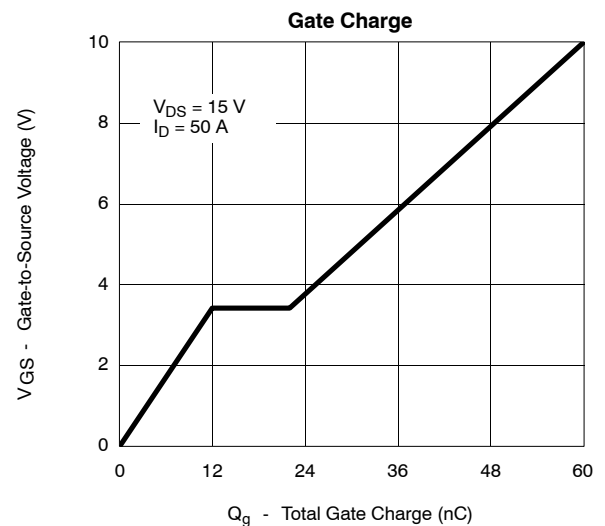
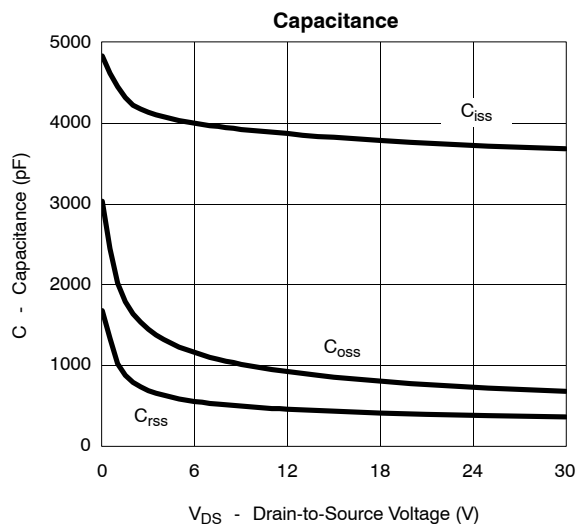
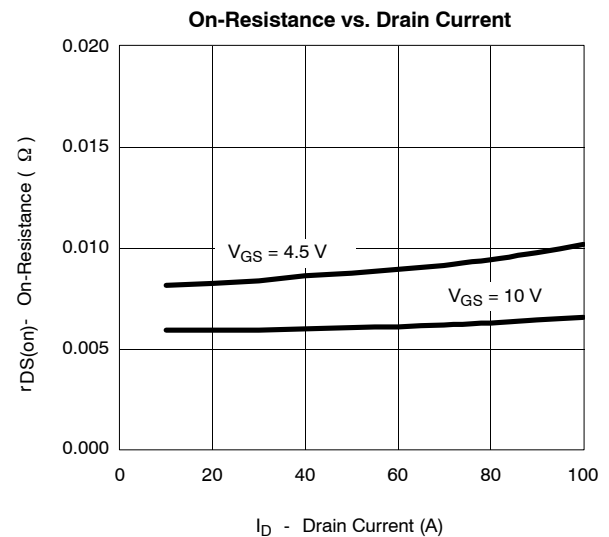
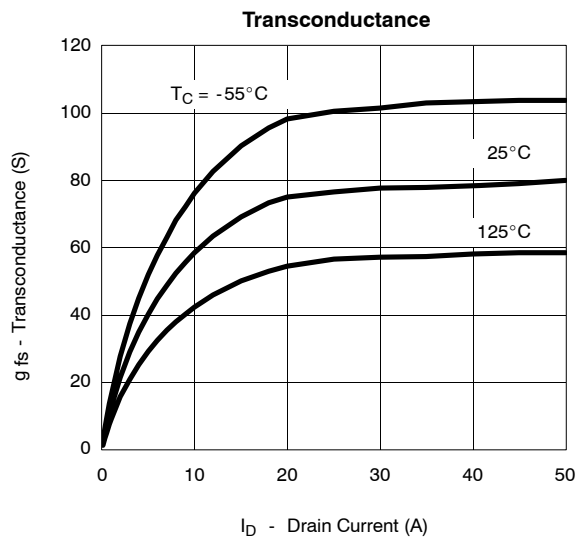
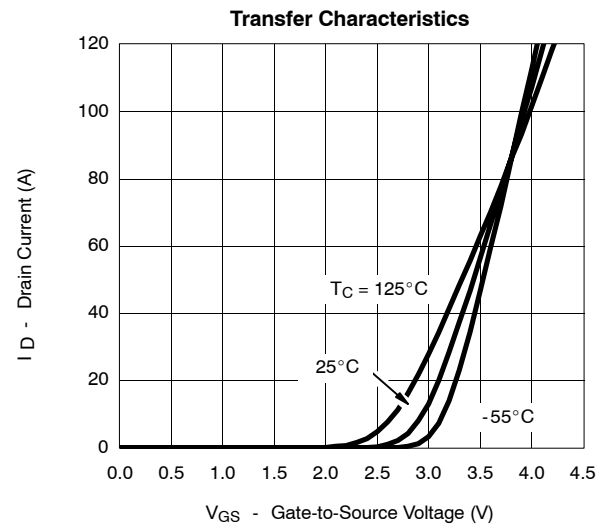
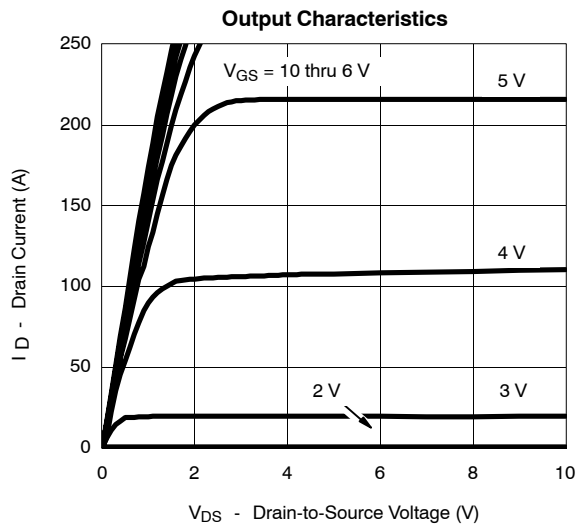
Notes

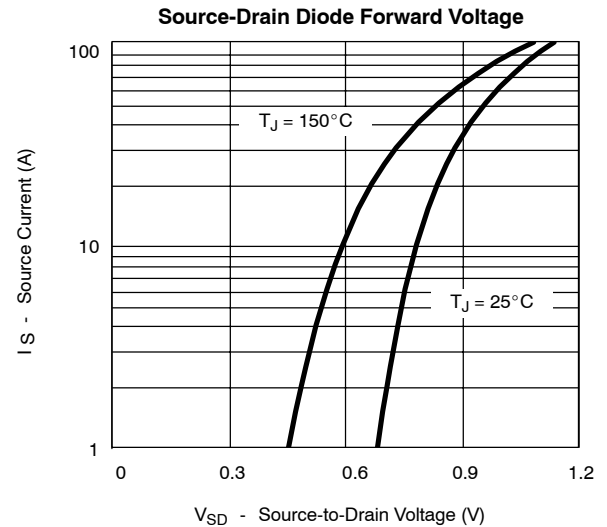
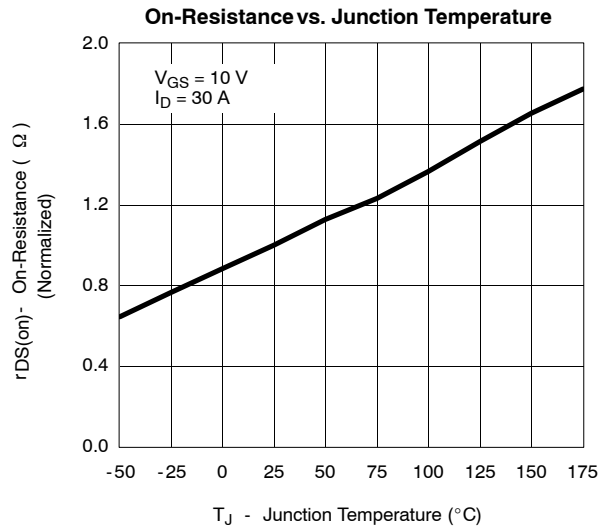
- Surface Mounted on 1" x 1" FR4 Board.
- $t \leq 10$ sec.
- Based on maximum allowable Junction Temperature. Package limitation current is 50 A.

SPECIFICATIONS (T _J = 25 °C UNLESS OTHERWISE NOTED)						
Parameter	Symbol	Test Condition	Min	Typ ^a	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0 V, I _D = 250 μA	30			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1.0	2.0		
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ±20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	μA
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 125 °C			50	
On-State Drain Current ^b	I _{D(on)}	V _{DS} = 5 V, V _{GS} = 10 V	50			A
Drain-Source On-State Resistance ^b	r _{DS(on)}	V _{GS} = 10 V, I _D = 20 A			0.007	Ω
		V _{GS} = 10 V, I _D = 20 A, T _J = 125 °C			0.011	
		V _{GS} = 4.5 V, I _D = 20 A			0.010	
Forward Transconductance ^b	g _{fs}	V _{DS} = 15 V, I _D = 20 A	20			S
Dynamic ^a						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, F = 1 MHz		3720		pF
Output Capacitance	C _{oss}			715		
Reverse Transfer Capacitance	C _{rss}			370		
Total Gate Charge ^c	Q _g	V _{DS} = 15 V, V _{GS} = 4.5 V, I _D = 50 A		28	45	nC
Gate-Source Charge ^c	Q _{gs}			12		
Gate-Drain Charge ^c	Q _{gd}			10		
Gate Resistance	R _g		0.5		3.3	Ω
Turn-On Delay Time ^c	t _{d(on)}	V _{DD} = 15 V, R _L = 0.3 Ω I _D ≅ 50 A, V _{GEN} = 10 V, R _G = 2.5 Ω		11	25	ns
Rise Time ^c	t _r			6	15	
Turn-Off Delay Time ^c	t _{d(off)}			50	100	
Fall Time ^c	t _f			11	20	
Source-Drain Diode Ratings and Characteristic (T _C = 25 °C)						
Pulsed Current	I _{SM}				100	A
Diode Forward Voltage ^b	V _{SD}	I _F = 100 A, V _{GS} = 0 V		1.2	1.5	V
Source-Drain Reverse Recovery Time	t _{rr}	I _F = 50 A, di/dt = 100 A/μs		45	100	ns

Notes

- a. Guaranteed by design, not subject to production testing.
b. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
c. Independent of operating temperature.

**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)**

TYPICAL CHARACTERISTICS (25°C UNLESS NOTED)**THERMAL RATINGS**